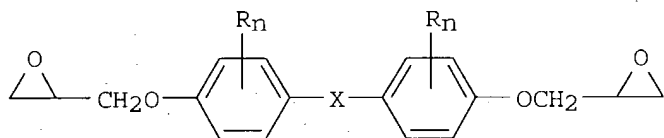


L Number	Hits	Search Text	DB	Time stamp
13	230239	(epox?\$3 near (resin\$ or novola?)) or diepox?3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 11:56
14	125	525/525.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 11:56
15	30788	thioether	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 11:56
16	917	sulfanyl	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 11:56
17	3184	((epox?\$3 near (resin\$ or novola?)) or diepox?3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$) and thioether	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 11:56
18	10	((epox?\$3 near (resin\$ or novola?)) or diepox?3 or polyepox?\$3 or diglycidyl\$ or polyglycidyl\$) and thioether) and 525/525.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/01 11:56

AN 1995:823657 CAPLUS
 DN 123:342003
 ED Entered STN: 30 Sep 1995
 TI Preparation of low-viscosity crystalline epoxy resins
 IN Kaji, Masashi; Aramaki, Takanori; Nakahara, Kazuhiko
 PA Shinnittetsu Kagaku, Japan
 SO Jpn. Kokai Tokkyo Koho, 5 pp.
 CODEN: JKXXAF
 DT Patent
 LA Japanese
 IC ICM C08G059-06
 CC 37-3 (Plastics Manufacture and Processing)
 Section cross-reference(s): 35

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
PI	JP 07179564	A2	19950718	JP 1993-347837	19931224
PRAI	JP 1993-347837		19931224		
GI					



AB The title resins are prepd. by mixing 100 parts liq. epoxy resin I (R = monovalent group; n = 0-4; X = divalent group) with 0.05-10 parts cryst. powd. I and crystg. the mixt. by stirring at a temp. .gtoreq.20.degree. below the m.p. of I. The resins are useful as potting compns., powder coating compns., adhesives, etc. A mixt. of 50 parts liq. epoxy resin prepd. from 120 parts bis(4-hydroxy-3,5-dimethylphenyl)methane and 960 parts epichlorohydrin was crystd. by stirring with 0.5 part powd. cryst. bis(4-glycidyloxy-3,5-dimethylphenyl)methane at 40.degree. for 40 min, giving a cryst. product m. 79.5.degree..

ST bisphenol epoxy resin prepn crystn
 IT Crystallization
 (in prepn. of low-viscosity cryst. epoxy resins using seed crystals)

IT Epoxy resins, preparation
 RL: IMF (Industrial manufacture); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PREP (Preparation); PROC (Process); USES (Uses)
 (use of seed crystals in prepn. of low-viscosity cryst.)

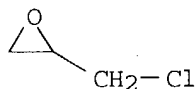
IT 113693-69-9P **158117-90-9P** 158663-92-4P
 RL: IMF (Industrial manufacture); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PREP (Preparation); PROC (Process); USES (Uses)
 (epoxy resins; prepn. of low-viscosity cryst.)

IT 26564-94-3P 93705-66-9P 170110-44-8P 170577-61-4P
 RL: IMF (Industrial manufacture); PEP (Physical, engineering or chemical process); TEM (Technical or engineered material use); PREP (Preparation); PROC (Process); USES (Uses)
 (seed crystals; in prepn. of low-viscosity cryst. epoxy resins)

RN 158117-90-9 REGISTRY
 CN Phenol, 4,4'-thiobis[2-(1,1-dimethylethyl)-5-methyl-, polymer with
 (chloromethyl)oxirane (9CI) (CA INDEX NAME)
 OTHER CA INDEX NAMES:
 CN Oxirane, (chloromethyl)-, polymer with 4,4'-thiobis[2-(1,1-
 dimethylethyl)-5-methylphenol] (9CI)
 OTHER NAMES:
 CN 2,2'-Dimethyl-5,5'-di-tert-butyl-4,4'-dihydroxydiphenyl
 sulfide-epichlorohydrin copolymer
 CN 2,2'-Dimethyl-5,5'-di-tert-butyl-4,4'-dihydroxydiphenyl
 thioether-epichlorohydrin copolymer
 CN Epichlorohydrin-4,4'-thiobis(2-tert-butyl-5-methylphenol) copolymer
 MF (C22 H30 O2 S . C3 H5 Cl O)x
 CI PMS
 PCT Epoxy resin, Polythioether
 SR CA
 LC STN Files: CA, CAPLUS

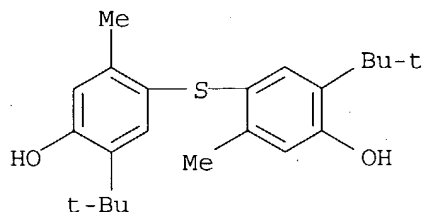
CM 1

CRN 106-89-8
 CMF C3 H5 Cl O



CM 2

CRN 96-69-5
 CMF C22 H30 O2 S



6 REFERENCES IN FILE CA (1907 TO DATE)
 6 REFERENCES IN FILE CAPLUS (1907 TO DATE)